

ABSTRACT

Improved method and apparatus for removing material from a surface of a workpiece including a low dielectric constant material are disclosed. The apparatus includes a platen, having
5 a polishing surface attached thereto, configured to orbit at more than about 500 revolutions per minute and a workpiece carrier configured to rotate and apply about 0.25 to about 2 psi. to the workpiece in the direction of the platen.

702740-92492860